

CENTRE FOR DEVELOPMENT OF ADVANCED COMPUTING

A Scientific Society of Ministry of Electronics & Information Technology,
Government of India

CDAC Knowledge Park, No. 1, Old Madras Road, Baiyypanahalli,
Bengaluru - 560038

Tel: +91-80-25093400

mmg-blrkp@cdac.in

www.cdac.in

Tender No: CDACB/BD24/004/005

CDAC, Bangalore invites bids for PCB Manufacturing & Assembly including
components procurement for Ubimote 2V3 and Ubisense 1V2

Prospective Bidders may download the Tender Document from www.cdac.in / <https://eprocure.gov.in/eprocure/app>. Bidders are advised to go through instructions provided at 'Instructions for online Bid Submission' and submit duly filled bids online on the website <https://eprocure.gov.in/eprocure/app> as per the schedule given in the Tender Document.

Section I: INVITATION FOR BIDS (IFB)

1. Introduction.

Centre for Development of Advanced Computing invites Request for Proposal (RFP) towards **PCB Manufacturing & Assembly including components procurement for Ubimote 2V3 and Ubisense 1V2**

2. Scope of Work:

The scope of work and specifications as detailed at Annexure I

3. Assistance to bidders:

Any query relating to the process of online bid submission or queries relating to CPP Portal in general may be directed to the 24*7 CPP Portal Helpdesk on :- 0120-4200 462, 0120-4001 002, 0120-4001 005, 0120-6277 787; e-mail for Technical - support-eproc@nic.in.

4. Contact Address:

Manager, Admin, (MMG)
Centre for Development of Advanced Computing
C-DAC Knowledge Park, No.1, Old Madras Road,
Byappanahalli, Bangalore-560038
Phone Nos.080-25093400, email : mmg-blrkp@cdac.in

5. Two e-bids System:

**The bids should be submitted Online through
<https://www.eprocure.gov.in/eprocure/app>:**

The two ebids system will be followed for this tender. In this system, bidder must submit their offer-online in separate packets as explained below:

- **Online-ePacket No.1:** "Technical Bid" shall contain(PDF format only)
 - a. Covering letter, as per **Annexure–A**.
 - b. Authority letter as per **Annexure–B**.
 - c. A self-attested copy of Certificate of Incorporation, Partnership Deed/ Memorandum and Articles of Association / any other equivalent document showing date and place of incorporation, as applicable of the bidder.
 - d. Copies of PAN and GST registration certificates of the bidder.
 - e. Duly filled Technical Bid with proper seal and signature of the authorized person (**with name, designation, email id & contact no.**).
 - f. Copies of similar Purchase orders and reports, as per eligibility criteria.

- g. Copies of documents in support of eligibility requirements stipulated at para 4 Section – II.
- h. A photocopy of Section – V of the bid (commercial bid) without prices (prices blocked). C-DAC reserves the right to reject the bid in case of discrepancy observed in the unpriced commercial bid and the actual commercial bid.
- i. Details local presence in Bangalore.
- j. Other documents necessary in support of eligibility criteria, product catalogues, brochures etc.
- k. **Undertaking from the supplier as per O.M. ref : F.No.6/18/2019-PPD of Public Procurement Division, Department of Expenditure, Ministry of Finance dated 23rd July 2020 and Order (Public Procurement No. 1) No. F.No.6/18/2019-PPD of Public Procurement Division, Department of Expenditure, Ministry of Finance dated 23rd July 2020 and further Order/OMs regarding restrictions on procurement from a bidder of a country which shares a land border with India as per **Annexure-C****

Note: C-DAC reserves the right to reject the bid if any of the above listed document/s is/are not submitted.

- **Online-ePacket2:**“Financial eBid”: (BOQ.xls format only)

The Financial e-Bid completed in all respects with Bidder name, email id, contact no. & Date in the BOQ.xls format attached. (In the space provided in theBOQ.xls as Bidder name/address etc.)

(END OF SECTION I)

SECTION II: GENERAL CONDITIONS OF CONTRACT (GCC)

1. Subject:

PCB Manufacturing & Assembly including components procurement for Ubimote 2V3 and Ubisense 1V2

2. Location, Order Placements & Payment by

Centre for Development of Advanced Computing
C-DAC Knowledge Park, No.1, Old Madras Road,
Byappanahalli, Bangalore-560038
Phone Nos.080-66116400-03

3. Delivery Period:

- 3.1 First 5 PCBs or 1-panel (which ever applicable) prototype assembled cards should be supplied to C-DAC for testing and evaluation within 30 from the date of P.O.
- 3.2 C-DAC will confirm the result of testing within 7 days for further process.
- 3.3 The complete order should be delivered within 7 days from the date of positive confirmation (Successful testing of functionality of the first set of modules) from C-DAC.

4. Eligibility Criteria:

- 4.1 The bidder should have a minimum of One (1) year of experience in the field of Printed Circuit Board (PCB) manufacturing and assembly as on the date of bid submission. Documentary evidence such as work orders or completion certificates should be submitted in support.
- 4.2 The bidder should have valid ISO 9001 certification. A copy the certificate should be enclosed with the bid.
- 4.3 The bidder should not be black-listed by any State/ Central Government, Government Department, PSU or an autonomous institute, as on date of submission of bids.
- 4.4 Physical presence in Bangalore.

Note: Before submission of the bid, the bidders may please verify the eligibility criteria and ensure fulfilment of all the terms and conditions. In the absence of scanned copies of documents / certificates under eligibility criteria above, the bid is liable to be rejected.

- 5. Exemptions:** If in the view of bidder, any exemption / relaxation are applicable to them from any of the eligibility requirements, under any Rules, process, Guidelines, Directives of Government of India, bidder may submit their claim for the applicable exemption /relaxation, quoting the valid Rule, process, Guidelines or Directives. In this case the bidder must submit necessary and sufficient valid documents along with the technical bid, in support of their claim. The relevant and valid certificates in support of claim of exemption must be submitted.

6. Amendment to Bidding Documents

- 6.1 At any time prior to the deadline for submission of bids, C-DAC may, for any reason, whether on its own initiative or in response to the clarification request by a prospective bidder, modify the bid document.
- 6.2 The amendments to the bid documents, if any, will be notified by release of Corrigendum Notice on www.eprocure.gov.in / www.cdac.in/ against this bid. The amendments/ modifications will be binding on the bidders.
- 6.3 C-DAC at its discretion may extend the deadline for the submission of bids if it thinks necessary to do so or if the bid document undergoes changes during the bidding period, in order to give prospective bidders time to take into consideration the amendments while preparing their bids.

7. Preparation of Bids: Bidders should avoid, as far as possible, corrections, overwriting, erasures or postscripts in the bid documents. In case however, any corrections, overwriting, erasures or postscripts have to be made in the bids, they should be supported by dated signatures of the same authorized person signing the bid documents. However, the bidder shall not be entitled to amend/ add/ delete/ correct the clauses mentioned in the entire bid document.

8. Offer Validity: Offers should be valid for minimum Ninety (**90**) days from the date of opening of the Technical Bid. A bid, valid for a shorter period, is liable to be rejected. C-DAC Bangalore may ask the bidders to extend the period of validity, if required.

9. Submission of Bids- Online PDF format only.

The Bid documents shall be neatly arranged and all pages should be numbered. There should not contain any terms and conditions, printed or otherwise, which are not applicable to the Bid. **The conditional bid will be summarily rejected**. Insertions, postscripts, additions and alterations shall not be recognized, unless confirmed by bidder's signature.

10. Bid opening and Evaluation of Bids

- 11.1 The valid technical bids will be opened online on CPPP Portal.
- 11.2 The technical bids will be evaluated in two steps.
- 11.3 The bids will be examined based on eligibility criteria stipulated at Para 4 of Section – II to shortlist the eligible bidders. The technical bids of only the short listed eligible bidders shall be evaluated based on technical requirements stipulated in the RFP.
- 11.4 The duly constituted Tender Evaluation Committee (TEC) shall evaluate the bids. The TEC shall be empowered to take appropriate decisions on minor deviations, if any.
- 11.5 During evaluation of the Bids, TEC at its discretion may ask the Bidder for clarification of its Bid. The request for clarification and the response shall be in writing, and no change in the prices or substance of the Bid shall be sought, offered or permitted. If required CDAC may invite the Bidders for technical presentation on the solution / product. During the process of evaluation of

bids, if any discrepancies are observed in the bid submitted, the bidders will be given an opportunity to clarify on same. If in the view of bidder, any change in quantity, or services is required or any additional items are required, for clearing the said discrepancy, the bidder has to arrange for said change and/or addition of material without any increase in the prices quoted.

11. Opening of Commercial Bids: The bidders whose technical bid is found to meet both the requirements as specified above will qualify for opening of the commercial bid.

The determination of the lowest bidder (L1) shall be made separately for each line item based on the quoted value, inclusive of all applicable taxes and duties. Evaluation will be carried out on an item-wise basis and the L1 bidder for each item will be determined individually.

12. Product Specifications & Compliance Statement: The bidder should quote strictly as per the tender specifications. A Statement of Compliance shall be given against each item in the prescribed format given in **Annexure I**. The compliance statements should be supported by authentic documents. Each page of the bid and cuttings / corrections shall be duly signed and stamped by the authorized signatory and is to be submitted along with the bid. Failure to comply with this requirement may result in the bid being rejected.

13. Award of Contract

- 13.1 C-DAC shall award the contract to vendor who has become L1 as per their pricing and C-DAC will issue Purchase Order.
- 13.2 However, C-DAC reserves the right and has sole discretion to reject the lowest evaluated bid.
- 13.3 If more than one bidder happens to quote the same lowest price, C-DAC reserves the right to decide the criteria and further process for awarding the contract, decision of C-DAC shall be final for awarding the purchase order

14. C-DAC's Right to amend / cancel

- 14.1 C-DAC reserves the right to amend the eligibility criteria, commercial terms & conditions, Scope of the works, technical specifications etc.
- 14.2 C-DAC reserves the right to cancel the entire tender at any stage without assigning any reasons thereof.
- 14.3 If the information provided by the bidder is found to be incorrect/misleading at any stage/time during the Tendering process, C-DAC reserves the right to reject all such incomplete bids.

15. Corrupt or Fraudulent Practices

- 15.1 It is expected that the bidders who wish to bid for this project have highest standards of ethics.
- 15.2 C-DAC will reject bid if it determines that the bidder recommended for award has engaged in corrupt or fraudulent practices while competing for this contract.
- 15.3 C-DAC may declare a vendor ineligible, either indefinitely or for a stated duration, to be awarded a contract if it at any time determines that the vendor has engaged in corrupt and fraudulent practices during the award / execution of contract.

16 Interpretation of the clauses in the Tender Document / Contract Document

In case of any ambiguity/ dispute in the interpretation of any of the clauses in this Tender Document, the interpretation of the clauses by Executive Director, C-DAC, Bangalore shall be final and binding on all parties.

- 17 **OPTION CLAUSE:** The Purchaser reserves the right to increase or decrease the quantity to be ordered up to 25 percent of tender quantity at the time of placement of contract. The purchaser also reserves the right to increase the ordered quantity up to 25% of the contracted quantity during the currency of the contract at the contracted rates.

18 General Instructions:

- a) C-DAC, Bangalore reserves the right to accept / reject / split the offers or cancel the whole tender proceedings at any stage without assigning any reason whatsoever. Offers through Email / Fax, etc and open offers shall not be accepted. Late / Delayed offers shall not be accepted under any circumstances. Incomplete offers will be rejected. In case the specified date for the submission of offers being a holiday or declared holiday for CDAC, the bid-closing deadline shall stand extended to the next working day up to the same time.
- b) CDAC shall not be responsible for delayed submission or non- submission of bid due to any reasons whatsoever. The bidders are requested to submit their bids much before date & time of submission, failing which CDAC shall not be responsible for any such technical problem.
- c) Any attempt of direct or indirect negotiations on the part of the bidder with the authority to whom he has submitted the tender or authority who is competent to finally accept / reject the same after he has submitted his tender or any endeavor to secure any interest for an actual or prospective bidder or to influence by any means the acceptance of a particular tender will render the tender liable to be rejected.
- d) **Unsatisfactory Performance: C-DAC, Bangalore, shall have the sole and absolute discretion to evaluate and assess the performance of the component(s) offered by the Bidder, whether at the preliminary or final stage. Should C-DAC, Bangalore, at any point during the pre-test and/or post-test phases, determine that the component(s) do not meet its requirements, standards, or expectations, it reserves the right to reject such component(s), either in part or in full, without incurring any liability, whether direct or indirect, and without any obligation to provide an explanation to the Bidder. The Bidder expressly agrees and undertakes to accept such decision of BEL, Bangalore, without protest or demur**
- e) **Disclaimer:** This Tender / Request for Proposal (RFP) is not an offer by C-DAC, Bangalore, but an invitation for bidder's response. No contractual obligation whatsoever shall arise from the RFP process.

f) Declaration:

The bidder would be required to give a certificate as below in his commercial bid.

“I/WE UNDERSTAND THAT THE QUANTITY AND THE SCOPE OF SERVICES PROVIDED ABOVE IS SUBJECT TO CHANGE. I/WE AGREE THAT IN CASE OF ANY CHANGE IN THE QUANTITIES /SCOPE OF SERVICES REQUIRED, I/ WE WOULD BE SUPPLYING THE SAME AT THE RATES AS SPECIFIED IN THIS PRICE BID. I/WE AGREE TO ADHERE TO THE PRICES GIVEN ABOVE EVEN IF THE QUANTITIES /SCOPE OF SERVICES UNDERGO A CHANGE”.

(END OF SECTION II)

SECTION III: SPECIAL CONDITIONS OF CONTRACT (SCC)

1. Price

- 1.1 The price quoted shall be considered firm and no price escalation will be permitted. (Except Govt. levies/Taxes).
- 1.2 The prices quoted must be "F.O.R.-CDAC, Bangalore" inclusive of allied charges till destination.
- 1.3 Bidder must indicate exact rate of applicable GST separately for each item, with the HSN Code, in the 'commercial bid format'. The bidder should exercise utmost care to quote the correct percentage of applicable duty and GST on each item. The GST at the time of supply of material shall be applicable. TDS@ 2% on the GST will be deducted at source on all supplies, services for value above Rs. 2.50 lacs. TDS Certificate to this effect will be issued by C-DAC in all such cases.
- 1.4 In case due to any error/ oversight, the GST rate quoted by the bidder is different than the actual rate as per the tariff, the bidder will not be permitted to rectify the error/oversight. The orders/ contract will be placed with the rate quoted by the bidder or actual tariff rate (as on placement of order), whichever is LOWER. The difference amount payable, if any, between the quoted rate and actual tariff rate shall be borne by the bidder
- 1.5 Notwithstanding the para 1.2 and 1.3 mentioned above, if GST is not quoted separately and the bid is silent whether GST is included or excluded in price, then for the purpose of evaluation of bids, the prices shall be taken as including GST. In this case, GST applicable, if any will be borne by the bidder/contractor.
- 1.6 The prices quoted must be including of packing, forwarding, insurance, loading/un- loading charges, and all incidental charges till destination.
- 1.7 The exact rate of taxes, charges currently applicable (as per Tariffs) must be mentioned in the 'commercial bid format'. The statutory taxes and duties applicable at the time of supply of material shall be applicable.
- 1.8 The responsibility, cost and risk of the consignment shall rest with the bidder till receipt of goods is acknowledged by the end user at C-DAC, Bengaluru/Bengaluru. However, such receipt/ acknowledgement shall not be treated as acceptance of goods

2. Payments :

- 2.1 **97% of the payment will be made within 30 days of Supply, installation & acceptance. Balance 3% payment will be made on the completion of One year OR against submission of Performance Bank Guarantee of equivalent amount from any Indian bank valid for 14 (fourteen Months)**
- 2.2 All statutory deductions like Income Tax, GST as applicable, other taxes and levies as per Rules etc. will be deducted from Contractor's bills.

3. **Liquidated Damages:** Any inordinate delay that could be attributable to party shall attract a Liquidated Damage at the rate of 0.5% (one percent) of the order value (of individual job work) for each fortnight, with a ceiling of 10% (Ten percent) of the order value.
4. **Confidentiality:** Contractor shall not divulge the information relating to the circuits, layout design, fabrication procedures, quality control methods etc., that are not in public domain and exclusively provided by C-DAC for C-DAC's own requirements, to any third party and shall not use for Contractor's own commercial purpose.
5. **Sub-Contract:** Bidder shall not sub-contract any work or part of that work contracted by C-DAC to others, or to a third party.
6. **Non-disclosure Agreement:** The technical information, drawings and other related documents given by C-DAC-KP in the course of the work should remain the property of Government of India, Ministry of Electronics and Information Technology. The given Material / Documents should not be used for any other purpose or be duplicated in any case. The successful bidder should execute Non Disclosure Agreement with CDAC.
7. **Jurisdiction:** The disputes, legal matters, court matters, if any shall be subject to Bangalore jurisdiction only.
8. **Purchase preference to Micro and Small Enterprises (MSEs):** Purchase preference will be given to MSEs as defined in Public Procurement Policy for Micro and Small Enterprises (MSEs) Order, 2012 dated 23.03.2012 issued by Ministry of Micro, Small and Medium Enterprises and its subsequent Orders/Notifications issued by concerned Ministry. If the bidder wants to avail the Purchase preference for services, the bidder must be the Service provider of the offered Service. Relevant documentary evidence in this regard shall be uploaded along with the bid in respect of the offered service. If L-1 is not an MSE and MSE Service Provider (s) has/have quoted price within L-1+ 15% of margin of purchase preference /price band as defined in the relevant policy, then 100% order quantity will be awarded to such MSE bidder subject to acceptance of L1 bid price. The buyers are advised to refer to the OM_No.1_4_2021_PPD_dated_18.05.2023 for compliance of Concurrent application of Public Procurement Policy for Micro and Small Enterprises Order, 2012 and Public Procurement (Preference to Make in India) Order, 2017.
9. **Preference to Make In India products:** (For bids < 200 Crore):Preference shall be given to Class 1 local supplier as defined in public procurement (Preference to Make in India), Order 2017 as amended from time to time and its subsequent Orders/Notifications issued by concerned Nodal Ministry for specific Goods/Products. If the bidder wants to avail the Purchase preference, the bidder must upload a certificate from the OEM regarding the percentage of the local content and the details of locations at which the local value addition is made along with their bid, failing which no purchase preference shall be granted.

Only Class-I and Class-II Local suppliers as per MII order dated 4.6.2020 will be eligible to bid. Non - Local suppliers as per MII order dated 04.06.2020 are not eligible to participate.

- 10. Force Majeure:** C-DAC may consider relaxing the penalty and delivery requirements, as specified in this document, if and to the extent that, the delay in performance or other failure to perform its obligations under the contract is the result of an Force Majeure. Force Majeure is defined as an event of effect that cannot reasonably be anticipated such as acts of God (like earthquakes, floods, storms etc.), acts of states / state agencies, the direct and indirect consequences of wars (declared or undeclared), hostilities, national emergencies, civil commotion and strikes at successful Bidder's premises or any other act beyond control of the bidder.
- 11. Arbitration:** In the event of any dispute or difference between the Parties in respect of any matter relating to or arising out of this Agreement, they shall endeavor to negotiate a mutually satisfactory solution. If solution cannot be reached within a reasonable time, the said dispute or difference shall be referred to a sole arbitrator to be appointed by the Centre Head of C-DAC, Bangalore Centre, Bangalore. The arbitration proceedings shall take place in Bangalore and be conducted in English language and governed by the provisions of the Arbitration and Conciliation Act, 1996.”
- 12. Indemnity:** The successful bidder shall indemnify, protect and save C-DAC from/against all claims, losses, costs, damages, expenses, action suits and other proceeding, resulting from/arising out of:
- Infringement of any law pertaining to intellectual property, patent, trademarks, copyrights etc. by the bidder or
 - Such other statutory infringements in respect of all the equipment's supplied by successful bidder, or
 - Caused due to any act/omission/performance/under or non or part performance/failure of the bidder.
- 13. Assignment:** Selected bidders/ Parties shall not assign, delegate or otherwise deal with any of its rights or obligation under this Contract without prior written permission of C-DAC.
- 14. Severability:** If any provision of this Contract is determined to be invalid or unenforceable, it will be deemed to be modified to the minimum extent necessary to be valid and enforceable. If it cannot be so modified, it will be deleted and the deletion will not affect the validity or enforceability of any other provision

(END OF SECTION III)

Annexure I
SECTION IV- SCHEDULE OF REQUIREMENTS

Scope of work: The scope of work includes manufacturing of Printed Circuit Boards (PCBs) based on the design and specifications that will be provided at the time of order placement. The bidder shall procure all required electronic components and assemble the PCBs

1. Once the order is released the bidder,
 - Should execute Non-Disclosure Agreement with C-DAC for which the format will be provided later.
 - Necessary data file with Gerber Data shall be provided along with the Contract.
 - Commence the process of Manufacturing of PCB after obtaining Gerber data form CDAC.
 - Procure all the components as per the part list/BoM.
 - Assemble the components on the PCBs as per the BoM and as per the special instructions, if applicable.
 - Do the basic post-assembly hardware testing as per the instructions (will be provided later) and provide test report of each card.
 - For the assembled PCBs which fail in basic post-assembly hardware testing at C-DAC, the vendor should take care of rework, repair and replacement of components at their cost
 - The time for repair, rework and replacement of components in the above case should not be more than 3 days
 - Vendor should mention a serial number for each card while supplying to C-DAC. The serial number should be unique across the batches of assembly.
 - All components should be RoHS compliant.
 - The assembly process should also be RoHS compliant.

Technical Specification and Compliance

Srl	Item Title	Item Description	Item Quantity	Compliance Yes / No	Remarks
1	PCB Manufacturing	Ubimote 2v3 – Specification as per Schedule A	200 Nos.		
2	Electronic Components	Electronic Components for Ubimote 2V3 – As per Schedule B	200 Nos.		
3	Assembly	Assembly of Electronic components Ubimote 2V3	200 Nos.		
4	PCB Manufacturing	Ubisense 1V2 - Specification as per Schedule C	200 Nos.		
5	Electronic Components	Electronic Components for Ubisense 1V2; As per Schedule D	200 Nos.		
6	Assembly	Assembly of Electronic components Ubisense 1V2	200 Nos.		

Schedule A

PCB Bare Board Specifications - Ubimote 2v3

Srl	Specification	Details	Compliance Yes / No	Remarks
1)	Board Size (mm)	40.00 x 50.00 mm		
2)	Distance b/w PCBs	0.079 inch / 2.0 mm		
3)	Panel Dim	54.00 x 64.00 mm		
4)	Material	FR4		
5)	Board Thickness	0.063 inch / 1.6 mm		
6)	Surface Finish	HASL (SnPb)/Electroless Nickel Immersion Gold (ENIG)		
7)	Solder Mask Bottom	Green		
8)	Solder Mask Top	Green		
9)	Legend Bottom	White		
10)	Peel Off	No		
11)	Carbon Contacts	No		
12)	Manufacturing Logo	No		
13)	Impedance Control	Yes		
14)	ET Symbol	No		
15)	Round Edge Plating	No		
16)	UL Sign	No		
17)	Data Approval	No		
18)	Electrical Testing	Yes		
19)	Board Separation	Breakrouting		
20)	Panel Border	0.197 inch / 5 mm		
21)	Layers	4 L		
22)	TG	High Tg (>= 170°)		
23)	Finish Cu Thickness	35.00		
24)	Inner Cu Thickness	35.00		
25)	Legend Top	White		
26)	Blind & Buried Via	No		
27)	Countersunk	No		
28)	Hard Gold (Gold tabs)	0.00		
29)	Serialization for PCBs	No		
30)	Via Fill	No		
31)	Special Buildup	Yes		
32)	Bevelling	No		
33)	Date Code	No		

Data file / Gerber file shall be provided at the time releasing the Contract.

Buildup Image the PCBs

Buildup Image
CuFoil-0.018
Prepreg-0.105
Core-1.20 (0.035/0.035)
Prepreg-0.105
CuFoil-0.018
Total thickness - 1.551

Schedule B

Specifications of Electronic Components for Ubimote 2V3 (required for 01 No. of Board)

Srl	Manufacturer Part Number	Description	Designator	Quantity	Compliance Yes / No	Remarks
1.	MCP73833-FCI_UN	Charge Management Li-Ion/Li-Pol	B1	1		
2.	DLM0NSM900HY2D	DLM0NSM_Y2D Series EMI Suppression Filter 90 at 100MHz 100mA 5V	B2	1		
3.	C0402C104K3PACTU	C0402 0.10 μ F X5R 10.00% 10 V	C1, C2, C3, C4, C5, C6, C11, C19, C23, C24, C29, C32	12		
4.	CL05A105KP5NNNC	Cap Ceramic 1uF 10V X5R 10% Pad SMD 0402 85C T/R	C7, C15, C18	3		
5.	GRT1555C1H221JA02D	Cap,Ceramic,0402,220pF 50V Murata 0402 GRM 220pF Ceramic Multilayer Capacitor, 50 V dc COG Dielectric +/-5% SMD	C8	1		
6.	GRM188R61A225ME34D	Cap Ceramic 2.2uF 10V X5R 20% Pad SMD 0603 85C T/R	C9, C10, C21	3		
7.	RF15N220J500CT	Chip Capacitor, 22pF +/-10%, 50V, 0402, Thickness 0.6 mm	C12, C13	2		
8.	GRM155R71H102KA01D	MURATA - GRM155R71H102KA01D - CAP, MLCC, X7R, 1NF, 50V, 0402	C14	1		
9.	RF15N120J500CT	Ceramic SMT capacitor 12pF 50Vdc Murata 0402 GRM 12pF Ceramic Multilayer Capacitor, 50 V dc COG Dielectric +/-5%	C16, C17	2		
10.	C3216X7R1E475K160AE	SMD Capacitor X7R(MURATA) with Capacitance: 4.7uF Tol. 10%. Rated Voltage: 25Vdc	C20	1		
11.	885012106012	Chip Capacitor, 4.7 μ F +/-20%, 10V, 0603, Thickness 1 mm	C22, C30, C31	3		
12.	GRM1555C1H470JA01D	Murata 0402 GRM 47pF Ceramic Multilayer Capacitor, 50 V dc, +125C, COG Dielectric, +/-5% SMD	C25, C26	2		
13.	0402YC103JAT2A	General Purpose Ceramic Capacitor, 0402, 10nF, 5%, X7R, 15%, 16V	C27	1		
14.	CL10A105KP8NNND	Cap Ceramic 1uF 10V X5R \pm 10% Pad SMD 0603 +85°C T/R	C28	1		
15.	SP1007-01ETG	No Description Available	d12, d13	2		
16.	SM0805GCL	SMT LED 0805 Green Clear Lens Bivar SM0805GCL Green High-Power LED, 574 nm 2012 (0805), Rectangle Lens SMD package	D1, D2, D3, D8	4		
17.	CDBU0530	DIODE SCHOTTKY 20V 500MA 0603	D4, D9, D11	3		

Srl	Manufacturer Part Number	Description	Designator	Quantity	Compliance Yes / No	Remarks
18.	LTST-C190KRKT	LED,SMD,0603,Red,54mcd,130deg Lite-On LTST-C190KRKT Red LED, 631 nm, 1608 (0603), Rectangle Lens SMD Package	D5	1		
19.	LTST-C190KGKT	Lite-On LTST-C190KGKT, 571 nm Green LED, 1608 (0603) SMD package	D6, D7	2		
20.	PRTR5V0U2X,215	Ultra Low Capacitance Double Rail-to-Rail ESD Protection Diode, 5.5 V, 1 pF, -40 to 85 degC, 4-Pin SOT143B, RoHS, Tape and Reel	D10	1		
21.	BLM18HE152SN1D	Chip Ferrite Bead, 0603, 1500Ω @ 100MHz, 0.5Ω, 25%, 500mA	FB1, FB2	2		
22.	BLM18PG121SN1D	Chip Ferrite Bead, 0603, 120Ω @ 100MHz, 0.05Ω, 25%, 2A	FB3	1		
23.	5-1814832-2	RF Connectors, SMA RF Interface, Jack, RF Connector Mated Outer Diameter (Approximate) .25 in [6.35 mm], 50 , Threaded, 3GHz Operating Frequency	J1	1		
24.	47589-0001	Right Angle Female Type AB Micro USB Connector, 30 V, 1.8 A, -30 to 85 degC, RoHS, Tape and Reel	J2	1		
25.	SBH11-PBPC-D07-RA-BK	No Description Available	J3	1		
26.	SBH11-PBPC-D05-RA-BK	No Description Available	J4	1		
27.	TS-102-T-A	No Description Available	J5	1		
28.	RC0603JR-070RL	RES 0 OHM JUMPER 0603	R1, R6	2		
29.	SFR01MZPF5602	RES SMD 56K OHM 1% 1/10W 0402	R2	1		
30.	ERJ-2RKF2201X	Precision Thick Film Chip Resistor, 2.2 kOhm, 100 mW, 1%, -55 to 155 degC, 2-Pin SMD (0402), RoHS, Tape and Reel	R3	1		
31.	CRCW040210K0FKED	Resistor;Thick Film;10 Kilohms;0.063 W;1%;SMT;0402;TCR 37 ppm/DegC;Tape and Reel	R4, R5	2		
32.	ERJ-2GEJ561X	Series/Type: Thick Film Chip Resistors, Power Rating (W): 0.1, Chip Size (LxW(EIA)) (mm): 1.0 x 0.5 (EIA:0402), Resistance Values (Ω,,	R7, R8, R9	3		
33.	AF0603JR-130RL	Res Thick Film 0603 0 Ohm Pad SMD Automotive T/R	R10	1		
34.	ERJ-2GEJ561X	Series/Type: Thick Film Chip Resistors, Power Rating (W): 0.1, Chip Size (LxW(EIA)) (mm): 1.0 x 0.5 (EIA:0402), Resistance Values (Ω,,	R11	1		
35.	ERJ-3EKF2210V		R12, R13, R14	3		
36.	CRCW060310K0FKEA	Resistor, Thick Film, 10 Kilohms, 0.1 W, 1%, SMT, TCR 37 ppm C, Tape and Reel	R15	1		
37.	ERJ-3EKF4701V		R16	1		

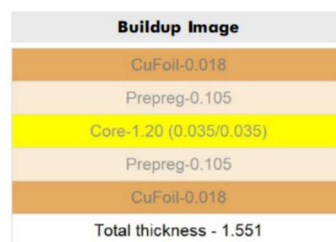
Srl	Manufacturer Part Number	Description	Designator	Quantity	Compliance Yes / No	Remarks
38.	CRCW040247K0FKEDHP	CRCW Power Resistor 0402 0.063W 47K	R17	1		
39.	CRCW040210K0FKED	Resistor;Thick Film;10 Kilohms;0.063 W;1%;SMT;0402;TCR 37 ppm/DegC;Tape and Reel	R18	1		
40.	RK73H1ETTP1501F	IC OPAMP VFB 170MHZ RRO 8SOIC	R19	1		
41.	RK73H1ETTP33R0F	Resistor SMD [KOA] RK73H1ETTP33R0F Resistor SMD	R20, R21	2		
42.	B3F-1000	Tactile Switch, SPST-NO, 0.05 A, 24 V, -25 to 70 degC, 4-Pin THD, RoHS, Bulk	SW1, SW2	2		
43.	GPBS-850L	No Description Available	SW3	1		
44.	CC2538SF53RTQT	No Description Available	U1	1		
45.	2450BM15A0002E	No Description Available	U2	1		
46.	W25Q80DVSNIG	No Description Available	U3	1		
47.	AP2127N-3.3TRG1	No Description Available	U4	1		
48.	CP2102N-A02-GQFN20	No Description Available	U5	1		
49.	FC-12M 32.7680KA-A3	No Description Available	XTAL1	1		
50.	FA-128_32.0000MF20X-K3	32 MHz \pm 10ppm Cristal 10pF 60 Ohms 4-SMD, sans plomb	Y1	1		

Schedule C

PCB Bare Board Specifications - Ubisense 1V2

Srl	Specification	Details	Compliance Yes / No	Remarks
1.	Board Size (mm)	23.06 x 40.01 mm		
2.	Distance b/w PCBs	0.079 inch / 2 mm		
3.	Panel Dim	137.30 x 96.02 mm		
4.	Material	FR4		
5.	Board Thickness	0.063 inch / 1.6 mm		
6.	Surface Finish	HASL (SnPb)/Electroless Nickel Immersion Gold (ENIG)		
7.	Solder Mask Bottom	Green		
8.	Solder Mask Top	Green		
9.	Legend Bottom	White		
10.	Peel Off	No		
11.	Carbon Contacts	No		
12.	Manufacturing Logo	No		
13.	Impedance Control	No		
14.	ET Symbol	No		
15.	Round Edge Plating	No		
16.	UL Sign	No		
17.	Data Approval	No		
18.	Electrical Testing	Yes		
19.	Board Separation	Breakrouting		
20.	Panel Border	0.197 inch / 5 mm		
21.	Layers	4 L		
22.	TG	High Tg ($\geq 170^\circ$)		
23.	Finish Cu Thickness	35.00		
24.	Inner Cu Thickness	35.00		
25.	Legend Top	White		
26.	Blind & Buried Via	No		
27.	Countersunk	No		
28.	Hard Gold (Gold tabs)	0.00		
29.	Serialization for PCBs	No		
30.	Via Fill	No		
31.	Special Buildup	Yes		
32.	Bevelling	No		
33.	Date Code	No		

Buildup Image the PCBs



Schedule D

Components required for 1 No. of (2) -Ubisense 1V2 Board (required for 01 No. of Board)

Srl	Manufacturer Part Number	Description	Designator	Quantity	Compliance Yes / No	Remarks
1.	GRM155R60J475ME87D	Chip Multilayer Ceramic Capacitors for General Purpose, 0402, 4.7uF, X5R, 15%, 20%, 6.3V	C1	1		
2.	CC0402KRX5R5BB105	CAP CER 1UF 6.3V X5R 0402	C2	1		
3.	593D106X9016A2TE3	593D106X9016A2TE3 Cap Tant Solid 10uF 16V A CASE 10% (3.2 X 1.6 X 1.6mm) SMD 3216-18 1.7 Ohm 125C T/R	C3	1		
4.	LMK105BJ104KV-F	CAP CER 0.1UF 10V X5R 0402	C4, C5, C6, C7, C8	5		
5.	SFH4650	EMITTER IR 860NM 100MA SMD	D1	1		
6.	LSR976-NR-1	LED RED DIFFUSED 0805 SMD	D2	1		
7.	SFH11-PBPC-D07-RA-BK	CONN HDR 14POS 0.1 GOLD PCB	J1	1		
8.	PH1-04-UA	CONN HEADER VERT 4POS 2.54MM	J2	1		
9.	ERJ-2GE0R00X	Chip Resistor, 0 Ohm, 0.1 W, -55 to 155 degC, 0402 (1005 Metric), RoHS, Tape and Reel	R1, R5, R6, R8, R9, R10, R11, R12	8		
10.	RE0402DR-071KL	RES 1K OHM 1% 1/16W 0402	R2, R3	2		
11.	ERJ-2RKF1501X	RES SMD 1.5K OHM 1% 1/10W 0402	R4	1		
12.	CRGCQ0402F22R	CRGCQ0402 220 1% ?200ppm/?C 50V	R7	1		
13.	ERJ-2GEJ561X	Chip Resistor, 560 Ohm, +/- 5%, 100 mW, -55 to 155 degC, 0402 (1005 Metric), RoHS, Tape and Reel	R13	1		
14.	ERJ-2RKF4701X	Chip Resistor, 4.7 KOhm, +/- 1%, 0.1 W, -55 to 155 degC, 0402 (1005 Metric), RoHS, Tape and Reel	R14, R15	2		
15.	CRCW0402-10K0FKED	RES SMD 10K OHM 1% 1/16W 0402	R16, R17	2		
16.	PS1240P02CT3	BUZZER PIEZO 3V 12.2MM TH	U1	1		

Srl	Manufacturer Part Number	Description	Designator	Quantity	Compliance Yes / No	Remarks
17.	2SC4116-BL,LF	TRANS NPN 50V 0.15A SC-70	U2	1		
18.	TSL27721FN	Light-to-Digital Converter with Proximity Sensing, 2.4 to 3.6 V, FN-6, Pb-Free, Reel	U3	1		
19.	SHT21	Humidity and Temperature Sensor, 2.1 to 3.6 V, -40 to 125 degC, 6-Pin DFN, RoHS, Tape and Reel	U4	1		
20.	DPS310XTSA1	SENSOR PRESSURE CAPACITIVE	U5	1		
21.	ADXL343BCCZ	3-Axis, +/-2 g / +/-4 g / +/-8 g / +/-16 g Digital MEMS Accelerometer with Digital Output, 1.6 KHz BW, Industrial, 14-pin LGA, Tray	U6	1		
22.	PCA9515ADP,118	Buffer, ReDriver 1 Channel 400kHz 8-TSSOP	U7	1		

SECTION V – PRICE BID

SECTION VI – UNPRICED BID / PRICE BOQ.xls (PLEASE DO NOT FILL IN THE PRICES)

The vendor shall quote for all the line items below table and the L1 shall be arrived based on the cumulative cost of all the works mentioned in the table below.

Name of the Bidder/ Bidding Firm / Company :													
PRICE SCHEDULE <small>(This BOQ template must not be modified/replaced by the bidder and the same should be uploaded after filling the relevant columns, else the bidder is liable to be rejected for this tender. Bidders are allowed to enter the Bidder Name and Values only)</small>													
NUMBER	TEXT	TEXT	NUMBER	TEXT	NUMBER	NUMBER	NUMBER	NUMBER	NUMBER	NUMBER	NUMBER	NUMBER	TEXT
Sl. No.	Item Description	Item Code / Make	Quantity	Units	Estimated Rate in Rs. P	BASIC RATE in Figures To be entered by the Bidder in Rs. P	GST (If applicable in Percentage)	GST Amount in Rs. P	HSN / SAC Code	TOTAL AMOUNT excluding taxes in Rs. P	TOTAL AMOUNT including taxes in Rs. P	TOTAL AMOUNT In Words	
1	2	3	4	5	6	7	8	9	10	11	12	13	
1	PCB Manufacturing, Assembly including component procurement												
1.01	Ultimate 2V3	item1	200.00	Nos	0.00			0.00		0.00	0.00	INR Zero Only	
2.01	Ubisense TV2	item3	200.00	Nos	0.00			0.00		0.00	0.00	INR Zero Only	
Total in Figures										0.00	0.00	INR Zero Only	
Quoted Rate in Words										INR Zero Only			

Note: Commercial bids must be offered in the format above.

Authorized Signatory:
Name and Title of Signatory:
e-mail:

Annexure – A: Covering / Tender Acceptance Letter

Date:

To:

The Executive Director
Centre for Development of Advanced Computing(C-DAC)
Bengaluru.

Subject: Submission of the Technical bid for PCB Manufacturing & Assembly including components procurement for Ubimote 2V3 and Ubisense 1V2

Dear Sir,

- 1) We, the undersigned, offer our bid for in response to your Tender Enquiry No. We are hereby submitting our proposal for same, which includes this Technical bid and the Financial Bid
- 2) I / We hereby certify that I / We have read the entire terms and conditions of the tender documents from Page No.1 to 27(including all documents like annexure(s), schedules (s), etc.), which form part of the contract agreement and I / We shall abide hereby by the terms / conditions/ clauses contained therein.
- 3) I / We have downloaded / obtained the tender document(s) for the above mentioned 'Tender/Work' from the web site namely www.eprocure.gov.in; as per your NIT / advertisement, given in the above-mentioned website(s).
- 4) The corrigendum(s) issued from time to time by your department / organization too has also been taken into consideration, while submitting this acceptance letter.
- 5) We hereby declare that all the information and statements made in this Technical bid are true and we accept that any misinterpretation contained in it, may lead to our disqualification.
- 6) We undertake, if our proposal is accepted, to initiate the Implementation activities towards supply of material and services, as stipulated in the referred RFP.
- 7) We would hold the terms of our bid valid for **90 days** as stipulated in the RFP document.
- 8) I /We do hereby declare that our firm has not been blacklisted / debarred by any Govt. Department / Public sector undertaking.
- 9) I /We certify that all information furnished by the our firm is true & correct and in the event that the information is found to be incorrect / untrue or found violated, then your department/ organization shall without giving any notice or reason thereof or summarily reject the bid or terminate the contract, without prejudice to any other rights or remedy.
- 10) We understand you are not bound to accept any Proposal you receive.
- 11) The undersigned is authorised to sign this bid document. The authority letter to this effect is enclosed.

Yours sincerely,

Authorized Signatory:
Name and Title of Signatory:
e-mail:Mobile No:

Annexure – B: Authority Letter

Date:

To:

The Centre Head,
Centre for Development of Advanced Computing
Bengaluru.

Subject: Authority Letter

Reference: Tender No. CDACB/..... dated.....

Dear Sir,

We, M/s _____ (Name of the bidder) having registered office at _____ (address of the bidder) herewith submit our bid against the said RFP document.

Mr./Ms. _____ (Name and designation of the signatory), whose signature is appended below, is authorized to sign and submit the bid documents on our behalf against said RFP

Specimen Signature:

The undersigned is authorised to issue such authorisation on behalf of us.
For M/s _____ (Name of the bidder)

Signature and company seal
Name
Designation
Email
Mobile No.

Annexure C

CERTIFICATE FROM BIDDER

Executive Director,
Centre for Development of Advance Computing,
C-DAC Knowledge Park, No.1, Old Madras Road,
Byappanahalli, Bangalore-560038
Phone Nos.080-25093400

Ref: Tender No:

We hereby certify that the goods being offered by us vide our proposal, comply with the provisions of order No. Order No P-45021/2/2017-PP (BE-II), dated 4th June, 2020(as amended), issued by Public Procurement Division, Department for Industry and Internal Trade, Ministry of Commerce & Industry, Gol, read with order number W-43/4/2019-IPHW-MeitY, dated 7th September, 2020 issued by IPWH division of MeitY, Gol.

We hereby certify the details pertaining to goods offered by us, as given below:

Sr. No	Item Description	Make & Model No.	Country of origin of OEM	Country of Manufacture of item	Country of Shipment	Percentage of local contents as defined by order number W-43/4/2019-IPHW-MeitY, dated 7th Sept, 2020 issued by IPWH division of MeitY, Gol
1	PCB Manufacturing, Components Procurement, Assembly of a) Ubimote 2v3 b) Ubisense 1V2					

We also certify that, we are not from a country sharing land border with India as defined in order No. F/No/6/18/2019-PPD dated 23 July 2020 issued by public procurement Division, Dept. of Expenditure, Ministry of Finance, Gol and the goods offered by us comply with the provisions of said order.

For (Name of bidder)
Authorized Signatory
Name & Designation:
Mobile No:

Annexure D

On your letterhead

Self-Certification under preference to Make in India order

CERTIFICATE

In line with Government Public Procurement Order No. P-45021/2/2017-BE-II dt. 15.06.2017 &P45021/2/2017-PP (BE-II) dated 28.05.2018, we hereby certify that we M/s are local supplier meeting the requirement of minimum local content (...%) as defined in above orders for the material against Tender Enquiry No. dated Details of location at which local value addition will be made is as follows:
Address.....

We also understand, false declarations will be in breach of the Code of Integrity under Rule175(1)(i)(h) of the General Financial Rules for which a bidder or its successors can be debarred for upto two years as per Rule 151 (iii) of the General Financial Rules along with such other actions as maybe permissible under law. Seal and Signature of Supplier

Thanking You

for M/s

(Authorized Signatory)

ANNEXURE-E
EMD DECLARATION CERTIFICATE

Date:

To:

The Executive Director
Centre for Development of Advanced Computing (C-DAC)
C-DAC Knowledge Park
#1, Old Madras Road
Byappanahalli
Bangalore 560 038.

Subject: Undertaking as per GFR – 2017, Rule 170(iii)

Dear Sir,

We, the undersigned, offer to Supply the -----as per tender at C-DAC Bangalore, in response to your Bid No-----. We are hereby submitting our proposal for same, which includes Technical bid and the Financial Bid. As a part of eligibility requirement stipulated in said tender document, we hereby submit a declaration in lieu of Earnest Money Deposit (EMD), as given below:

1. Our bid shall remain valid for 90-days from the date of submission and that we will not withdraw or modify our bid during the validity period,
2. In case, we are declared as successful bidder and an order is placed on us, we will submit the acceptance within 5 days of placement of order on us.
3. In case of failure on our part to comply with any of the above said requirements, we are aware that we shall be declared as un-eligible for said tender and /or debarred from any future bidding process of C-DAC for a period of minimum one year.
4. The undersigned is authorized to sign this undertaking.

Yours sincerely,

Authorized Signatory:

Name and Title of Signatory:

e-mail:

Mobile No:

DOCUMENTS CHECK-LIST

Sl. No	Document	Page Numbers	Yes/No
	e-Packet – A		
1.	Covering Letter / Tender Acceptance letter (Annexure-A)		
2.	Authority Letter (Annexure-B)		
3.	A self-attested copy of Partnership deed / Memorandum and Articles of Association as applicable.		
4.	Self-attested copies of GST registration certificate, as applicable.		
5.	A self-attested copy of PAN card, if applicable		
6.	Self-certified copy of Balance Sheets/ Certificate from CA towards certification of turnover.		
7.	Technical Bid - Duly filled compliance statements		
8.	Undertaking from the supplier as per Annexure – C		
9.	Self-Certification under preference to Make in India order as per Annexure - D		
10.	EMD Declaration Certificate- Annexure-E		
11.	Copies of purchase orders and completion reports, as per eligibility criteria and any other documents in support of eligibility showing experience / relevant exemption certificate.		
12.	Documentary evidence of having local presence in Bangalore.		
13.	Valid ISO 9001 Certificate		
14.	Declaration letter 1) Bidder is not black-listed by any State/ Central Government, Government Department, PSU or an autonomous institute 2) Bidders financial standing.		
15.	Copy of Un-priced commercial bid		
16.	Any other supporting document		

	e-Packet – B		
1	Commercial bid (BOQ.XLS)		

(END OF DOCUMENT)